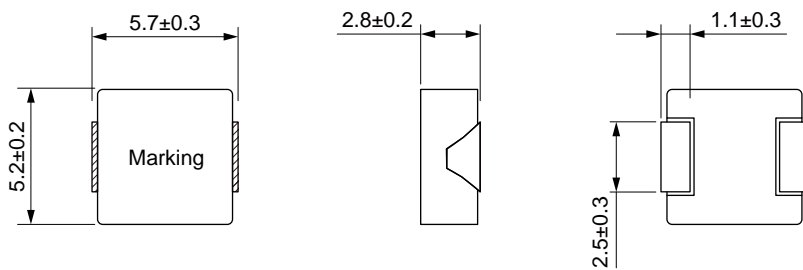


**MDA Series**  
**SMD Low Profile High Current Molded Inductor**  
**Size 5030**

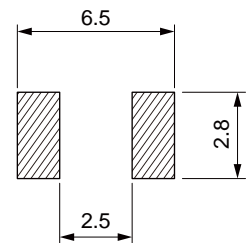
**FEATURES**

- 
- Capable of corresponding high frequency .
- Low loss realized with low DCR.
- High performance (Isat) realized by metal dust core.
- 
- 
- 
- 
- 

Dimensions: [mm]



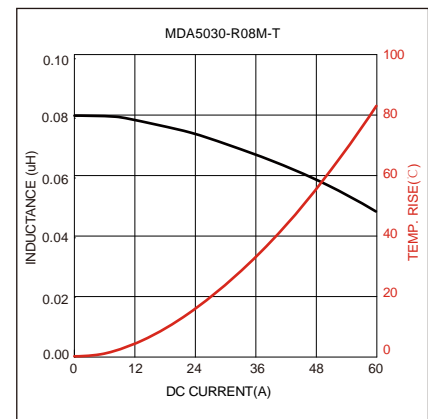
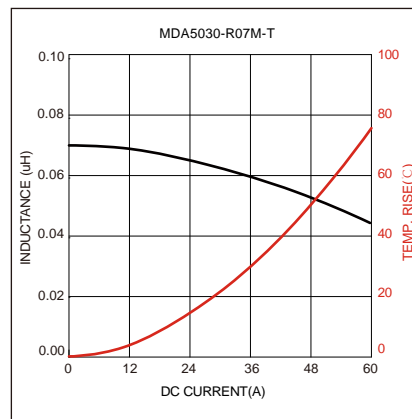
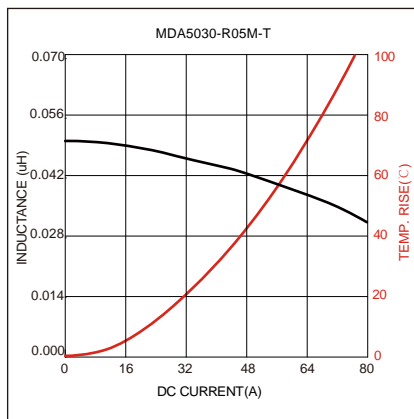
Land Pattern: [mm]



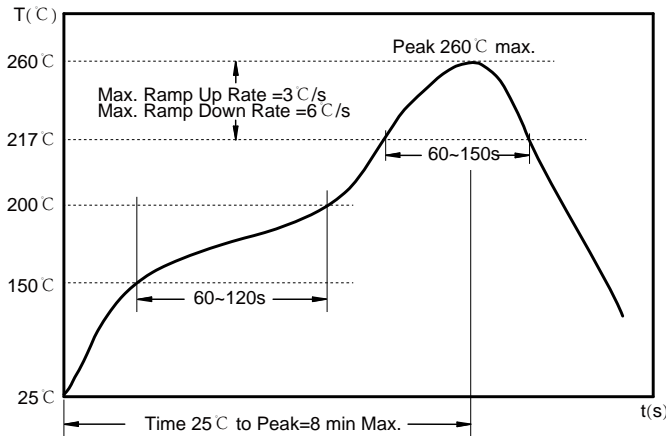
Electrical Properties:

| MDA5030-R05M-T | 0.05 | ±20% | 46 | 68 | 0.57 | 0.63 |
|----------------|------|------|----|----|------|------|
| MDA5030-R07M-T | 0.07 | ±20% | 42 | 52 | 0.64 | 0.71 |
| MDA5030-R08M-T | 0.08 | ±20% | 40 | 50 | 0.74 | 0.85 |

## Typical Electrical Characteristics:



## Soldering Reflow:



Preheat condition: 150 ~200°C / 60~120 sec.

Allowed time above 217°C : 60~150 sec.

Max temperature: 260°C .

Max time at max temperature: 10 sec.

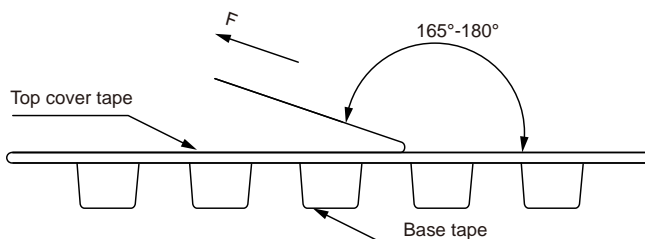
Allowed Reflow time: 2x max.

## Packaging Information:

### Tape Dimension :

| Series    | A0 (mm)  | B0 (mm)  | D (mm)   | P0 (mm)  | P1 (mm)  | W (mm)    | K0 (mm)  | E (mm)    | T (mm)     |
|-----------|----------|----------|----------|----------|----------|-----------|----------|-----------|------------|
| MDA5030-T | 5.5± 0.1 | 6.2± 0.1 | 1.5± 0.1 | 4.0± 0.1 | 8.0± 0.1 | 12.0± 0.3 | 3.3± 0.1 | 1.75± 0.1 | 0.35± 0.05 |

### Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

### Product Marking:

|         |                             |
|---------|-----------------------------|
| Marking | Printing Inductance+period) |
|---------|-----------------------------|

Reel Dimension: [mm]



Packaging Quantity: